Transaction Information

Tool ID	STP2353
Tool Status	Connected
Location	Malta, USA
Wafer Size	300 mm
Fab Section	Lithography
Tool Available Date	2024-11-20

General Product Information

Vendor Supplier	ASML
Model	NXT1950i PEP
Vintage	2011
Serial No	m3550
Asset Description	ASML NXT1950i immersion scanner with PEP
Software Version	6.3
CIM	SECS, GEM
Process	Litho

Hardware Configuration (Fab)

System Type	Description	Quantity	Status
Handler System	N/A		OK
Factory Interface	SMIF	2	OK
Others			
Main System	Scanner	1	
Options System			

Hardware Configuration (Subfab / Auxilliary Units)

Description	Quantity	Status
Entegris Liquid Lens	1	OK
PowerVAR	1	OK
ACC Donaldson Filter Cabinet	1	OK

Missing/Faulty Parts / Accesorries List

Description	Quantity
NONE	

Tool Pictures

General	Fab tool

General	Fab tool

Hardware Sub-fab	NONE

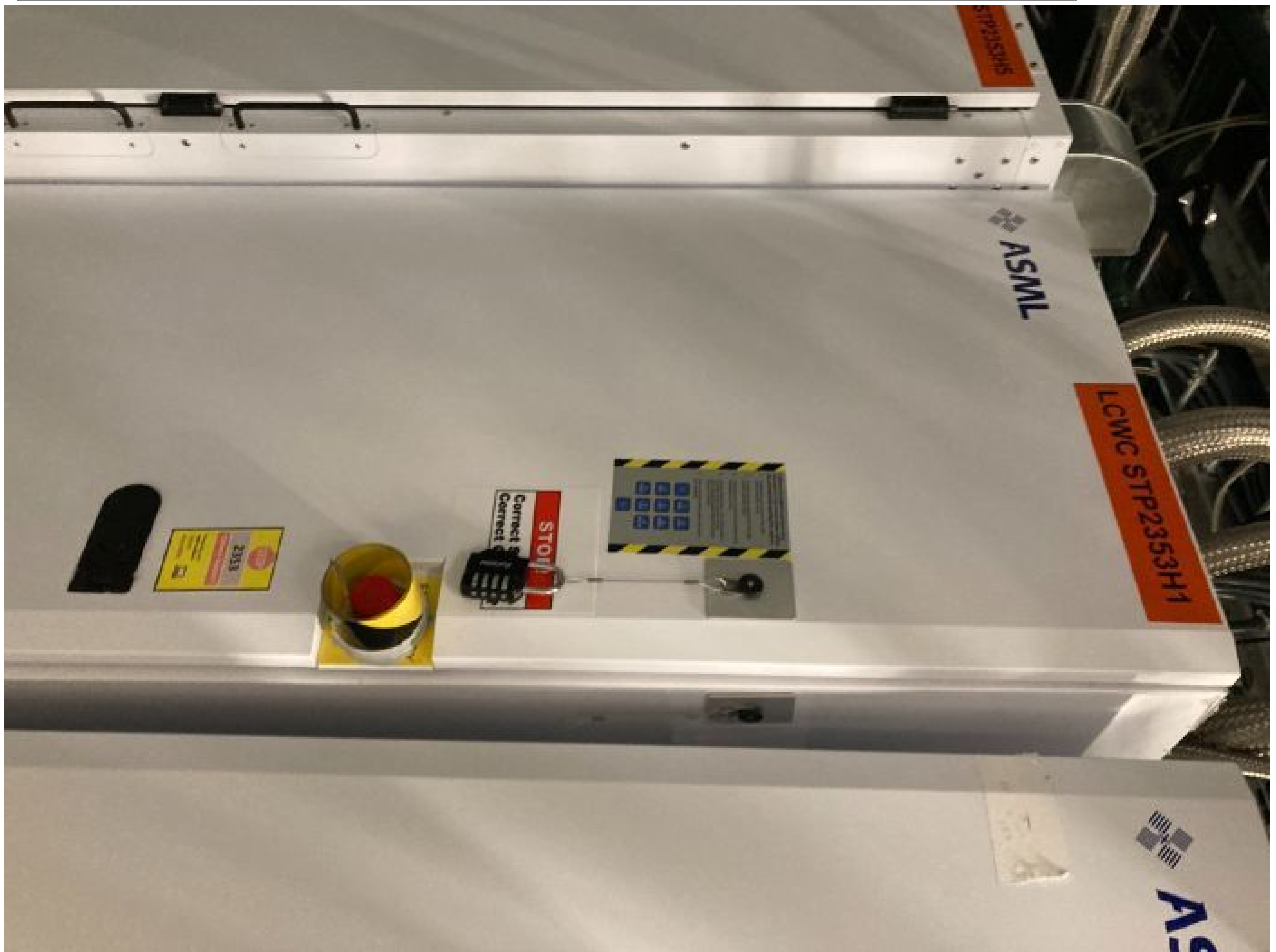
Hardware Sub-fab	NONE

Hardware Sub-fab	NONE

Hardware Sub-fab	NONE

Hardware Sub-fab	NONE

Hardware Sub-fab	NONE



Hardware Sub-fab	NONE

Hardware Sub-fab	NONE

Hardware Sub-fab	NONE

Hardware Sub-fab	NONE

Hardware Sub-fab	NONE

Manufacture Serial	NONE

Additional Tool Data Files

Parameter	Metadata	STP2353
(DUV) Reticle Handler Robot Barcode Reading Position		Original robot position to read reticle barcode
(DUV) Reticle Handler Robot Damper Hardware Configuration.		Robot does not include a mass damper.
2D Barcode Reader		Present
2D Barcode Reader at Load Port		2D Barcode Reader option is disabled
4par COWA allowed leveling strategies		4par COWA with LDL and LIL leveling strategy is allowed
A Focus Calibration Method using CDM or CDM3 model		A Focus Calibration Method with the CDM model
AA processing rack		MMCR processing rack
ALE 1 Use		NA
APACE used in production.		APACE is disabled in production.
APAXLE mode of operation		APAXLE is not controlled
Ability to use remote test service		Remote test service is enabled
Activate ESO MAX speed Allowed. Protected		ESO MAX Speed Allowed Disabled
Activation of the airknife during hovering		Airknife disabled during hovering in wet mode
Active Pupil Aberration Correction Element type		APACE type 1
Active Pupil Aberration Correction lens Element		Metrology uses one APACE with optics C
Active Set DLM, various improvements and Image Tuner fix		DLMv2.0
Active wafer release for dry WS		
Actuation mode for SBC Overlay corrections		DEFAULT
Agile NXE matching algorithms for NXE systems		Disabled
Air Gauge		Present
Air Gauge Improved Levelling		AGILE2
Airmounts hardware type		MK 4.2 with airtank
Alignment Camera Mirror		NA
Alignment Recipe Override		Alignment Recipe Override Disabled
Alignment Sensor Type		Smash OM
Alignment Strategy ID Standard or Extended. Protected.		Alignment Strategy ID max length is 15 characters
Alignment White light Source Wavelength Configuration		None
Alignment laser configuration		4 color laser
Alignment marks segment used during HSA on PARIS		NA
Alignment overlay and TPT node		Alignment Overlay and TPT Performance node 19
Allow L1L7 Type 1 Optimization		Absent
Allow different Exp,TIS Align set		Present

Allow even orders usage		Present
Allow wafer plane deviation check with Focus Monitoring		Disabled
Allowed wafer load grid improvement level		Until Level 1
Alternate RH robot firmware selection		Disabled
Angular sensitivity corrections of ESCAL sensor on Chuck 1		Disabled
Angular sensitivity corrections of ESCAL sensor on Chuck 2		Disabled
Angular sensitivity corrections of Spot Sensor on Chuck 1		Enabled
Angular sensitivity corrections of Spot Sensor on Chuck 2		Enabled
Application Specific Lens Heating Calibration & Verification		Present
Application Type		Scanner Application
Apply RBF Relaxation		Disable RBF Relaxation
Apply clamping grid correction during wafer align		disabled;
Apply grid corrections on unidirectional marks		Use zero to correct unmeasured directions
Assure System Snapshots		Assure System Snapshots not allowed
Asynchronous flexwave control during exposure		NA
Athena Focus Improvements 1		Present
Athena Narrow Marks Twinscan		Present
Attenuator Mirror Type		Quartz Attenuator Mirror
Attenuator Type		Variable
Automated DOE Exchanger		Absent
Automated DOE Exchanger Architecture		16 slots
Automated Lens Heating Calibration		Enabled
Automated Reticle Transport System		Light Curtain
Automatic CUA		Absent
Automatic CUA exchanger architecture		Adjacent to the Rema objective
Automatic PCE exchanger		Present
Availability of chucks in the waferstage compartment.		Both chucks are present.
Availability of inline grid-jump detection @ expose.		Grid Jump Detection at Expose functionality not available.
Availability of the FlexWave module		FlexWave module not available
Avoid I1 or I2 mark on TIS plates		Enabled;
Avoid Track INPUT/OUTPUT conflicts, Raise AS after APR		Avoid Track INPUT/OUTPUT conflicts enabled
BALE Type		Piezo Valves
BES switching behavior		Controlled by CEX
BMU Hardware version		Version 2

Backup method for machine data		Legacy, using asml_backup_settings
Barcode Reader at Load Port		There is no barcode reader at the load port
Barcode Reader configuration at IRL.		Omron 2D camera present at IRL.
Barcode Reader near the internal reticle library		Barcode reader is HAWKEYE type
BaseLiner Optima WEC/REC Control		BaseLiner Optima WEC/REC application is enabled.
BaseLiner focus control.		BaseLiner-Focus application is enabled.
BaseLiner focus high order intrafield		BaseLiner-Focus high order intrafield is disabled.
BaseLiner overlay control.		BaseLiner-Overlay application is enabled.
BaseLiner overlay high order intrafield		BaseLiner-Overlay high order intrafield is enabled.
Baseframe accelerometer box		Absent
Baseliner Astigmatism based focus stability control.		Disabled
Baseliner MMO focus stability control		Baseliner MMO focus stability control is disabled
Baseliner MMO overlay stability control		Baseliner MMO overlay stability control is disabled
Baseliner diffraction based focus stability contro		Baseliner diffraction based focus stability control enabled
Beam Control		Closed loop
Behavior of the FlexWave module		FlexWave not controllable
Bubble Extraction Seal Setting		NA
CD-FEC/FWOL spots selection corrections		Sub-optimal in corner cases
CDC		Enabled
CDU Optimizer generic dose corrections		Disable generic CDU Optimizer
CEX park decision version		Use park decision version 0
COWA with a 6-parameter model		Disabled
CTC type per recipe layer definition.		Disabled
Carrier Handler Type		Mark III 300
Choice of avoidance routing.		Phase 5
Choice of horizontal stage align setpoint		Reuse previous vertical stage align result
Chuck 1 wafer size		300mm
Chuck 2 wafer size		300mm
Chuck Dedication		Enhanced
Chuck specific calibration of field curvature.		Disabled
Circuit Dependent - Focus Edge Clearance application mode		Mode1: CDFEC is ON when yield. AND non-yield. dies present
Circuit Dependent FEC		Present
Clean Air Configuration		NA
Clean Air Temperature Control		NA
Clean Air Temperature Performance level		NA
Combined stage alignment		Enabled
Communication with Air Control Cabinet		RS232 communication

Computational ASCAL		Commercial cASCAL option enabled
Concatenation of actions prior to exposure		NA
Conditionally reset the POB		Include POB in system reset
Configuration Identification CARM Stages Stack		Version 0
Configuration identification CARM Handlers Stack		No Configuration Specified
Configuration identification for AMCR electronics		Config 1
Configuration identification for GPAB electronics		No configuration specified
Configuration identification for GPAS electronics		No configuration specified
Configuration identification for SACR electronics		No configuration specified
Configuration identification for WH part of the SACR Rack		No configuration specified
Configuration identification for immersion electronics		Config 2
Configuration identification reticle positioning electronics		Config 3
Configuration identification wafer positioning electronics		Config 10
Configuration identifier planar stage chuck 1 linear axis		Version 2
Configuration identifier planar stage chuck 1 long stroke		Version 2
Configuration identifier planar stage chuck 1 short stroke		Version 5
Configuration identifier planar stage chuck 2 linear axis		Version 2
Configuration identifier planar stage chuck 2 long stroke		Version 2
Configuration identifier planar stage chuck 2 short stroke		Version 5
Configuration of planar stage chuck 1 corner-cubes		Normal
Configuration of planar stage chuck 2 corner-cubes		Normal
Configuration of the IRPR electronics rack		No IRPR electronics rack present
Constrained fit		Disabled
Continuous clampable wafer table for dry WS		Absent
Control CS_event_check behavior		CS_event_check will block tools if active events exist
Control dose offset per field per wafer		Disable the control of dose offset per field per wafer
Core switch hardware type		No core network switch hardware present
Corr. Per Exposure Lot reporting includes ADELsbcoverlay.		Include the ADELsbcoverlay intrafield contribution.
Correct system drift using semi-active lens		Disabled

elements		
Correct system drift using semi-active lens elements.		NA
Crosstalk between RSC shape and Z/Ry on product		NA
DEPRECATED Alignment marks segment used during HSA on PARIS		Default
DMCR rack configuration		No DMCR configuration specified
DOSEMAPPER		Present
DOSE_MAPPER_1		Present
DP Storage Backend		Use DDDB as storage backend
DUV Lightsource Power Level		60.00 Watt
Data Handling Host VP item		Data Handling Host is absent.
Data Trace Manager Toolkit		Motif toolkit
Data collection not covered by FOCUS and OVERLAY		Enabled
Decides if the task queue can contain CPDs or only LOTs		Only allow LOTs to be queued in the task queue
Decides to correct the WSCS-WCS offset		NA
Dedicated Stage Alignment		Disabled
Defines the type of data that is restored		Restore settings and calibration data
Depolarizer type		no retarder but pce-depolarizer
Depth of Focus enhancement with adjustable laser bandwidth		Laser bandwidth is not adjustable
Describes at what plane the BMU measures		Correct for BMU below DOE1 level
Determination of NA ellipticity		Disabled
Determines leak detection configuration for the LCW circuit.		No leak detection.
Diaphragm Limiter		Absent
Differentiate between different HIB boards		Three HIB186 boards to determine the positions of the NeXZ
Disable Alignment Laser Configuration		Configuration will not support disabling of alignment lasers
Disable or enable an advanced ESO algorithm		No advanced ESO algorithm is enabled
Disable or enable the encryption of Recipes send to the Tool		Do not encrypt any recipes or layer files on Tool.
Docking wheels at WH unload		Absent
Dose Correction per Pupil Shape		Disabled
Dose Intensity Optimization		NA
Dose System Performance Test for Lithoguide		Present
DoseSystemPerformanceTest sequence		Test sequence 1
Dosecontrol Hardware		DCB
Dynamic Performance Calculation		Mark 3
Dynamic Performance Calculations with		Enable Trapezoid slit profile

Trapezoid slit profile		
Dynamics Edge Clearance		Dynamics Edge Clearance is supported
E-chuck Flatness Qualification Test		Disabled
EDA Interface		Enabled
EDA Interface standard Freeze		Level I
EDO		Disabled
EFESE		Absent
ENNE Data Collection		Disabled
ER hotlist promotion		Promotion to secs with a generic EXID and ALID
ESCAL execution in wafer production sequence		Not applicable - no ESCAL sensor
ESCAL sensor on chuck 1 present		No ESCAL sensor on chuck 1
ESCAL sensor on chuck 2 present		No ESCAL sensor on chuck 2
ESO Manual Override		ESO Manual Override Disabled
EXE Architecture Revision		None
Editable M-action queues		Editable M-action queues enabled
Electronics-box version of chuck 1		Version 2
Electronics-box version of chuck 2		Version 2
Embedded board diagnostic functionality		Disabled
Enable ExpoFlex functionality		ExpoFlex is available
Enable FIF functionality		FIF functionality is enabled
Enable FIP2 via recipe switch		NA
Enable the Maintenance Assistant		NA
Enable to support SMASH XY mark types.		SMASH XY marks are supported.
Enable/Disable HRG cooling		NA
Enable/Disable Oblique SBO drift for the Alignment Sensor		NA
Enable/Disable SBC2 contribution for SLM calibration		SBC2 contribution not used for SLM calibrate
Enable/disable FIWA route stability strategy for 2-opt		FIWA route does NOT use NN-Fix and presort algorithm.
Enabling Dynamic Performance Monitoring improvements		Enable DPM improvements
Energy Sensor		Star TechC
Energy sensor calibration type. Protected		NA
Enhanced Exposure Overlay		Full
Enhanced exposures 1		Present
Enhancements in Reticle Monitor		move feedback inspection overview
Equipment Constants via SECS interface		Enabled
Event Viewer Toolkit		Motif toolkit
Exception Reporting via EDA Interface.		NA
Exchangeable Last Lens Element		Present

Exchangeable Pupil Lens Element		Present
Exchangeable Pupil Lens Element Type		EPLE Type INACTIVE
Exclude AG to LS offset in AGILE2 AG measurement profile		NA
Extend IRIS maximum particles scanned to 50000.		Present
Extended LS areas		Disabled
Extended Lens Heating History (ELHH)		Enabled
Extended Range Leveling for UVLS		Default
Extended Spot Sensor Matching		Present
Extended Wafer Coverage control		Always on
Extended Zone Alignment		Disabled
Extended maximum for FILS Timeout.		Standard
Extended measurements after expose		NA
Extended minimum for FILS Timeout.		Standard
FIWA Route optimization method		Use 2-opt algorithm on mark distance
FOCAL Measurement for Lithoguide		Present
FSM Flexibility package		Disabled
FSM behavior if Extended Wafer Coverage is enabled for lot		FSM excludes EWC
Fallback type for GLC		No fallback specified for GLC
Field Dependent DOE Exclusion library		NA
Field curvature usage in standalone WBW correction		NA
Field width optimised leveling		Enabled
Filtering of the SUSD correction.		Filtered SUSD correction is disabled.
Fix Encoder drift scan path for NXT3 systems with PEPC		NA
Fix SbO bistable behavior		Coarse capture for HSA of first wafer on the chuck
FlexPol hardware		FlexPol HW is absent
FlexRay Control Rack Configuration		FSCR1
FlexWave Mode for Production		NONE - FlexWave is not used for production
Flexray Fluence Protection 60W		Enabled
Flexray illuminator		Flexray Freeform Mode
Flexwave (2DM) Manifold version		MK1 or MK2
Flexwave exhaust type		Unknown exhaust type
Focus Data Collection		Present
Focus Edge Clearance per Layer		Disabled
Focus Monitoring		Present
Focus Optimizer High Order correction support.		Disabled
Functional use of Active Elements		BALE function as BALE
GOAB firmware with redundant HFmap		GOAB firmware with singular HFmap storage (no

storage (if applicable).		redundancy).
GPAS sensor type at expose		Not applicable
GPAS sensor type at measure		Not applicable
GPMS reflectivity		Low reflectivity
GWS settings for Imm Hood 6.1 and low gas knife systems.		NA
Gac Algorithm selection for ORION		Default Gac algorithm
Gas Facilities Main Component		GFDU
Gas Facilities: Gas Supply Lens Manipulator		Gas supply lens manipulator hardware not present
Gas Facility / Airknife: Point Of Use Humidifier		NA
Graphical Toolkit for MC/FC/TE Constants Editors		Motif toolkit
Green Laser Attenuation feature		Not Allowed
GridPlate Accelerometer Box		GridPlate Accelerometer Box is absent
GridPlate Active Stiffness damper		Active stiffness units are absent
Gridmapper		Enabled
Hardware configuration identification of balance mass		Balance Mass with 6 DOF Linear Axis
Hardware configuration identification of wafer clamps		Venturi and CF unit MK3
Hardware configuration identification of wafer table clamp		Venturies
Hardware configuration of LoS2BM actuator version		Version 2 (Mk3.0/Mk3.1 actuator)
Hardware configuration of SS actuator of chuck 1		Version 2
Hardware configuration of SS actuator of chuck 2		Version 2
Hardware setting for wafertable BES flow		Wafer table BES at 30 Nl/min
Hardware version of Data Handling Host		Absent
Hardware version of Scanner Control Host		x86 mk2.x SSD
High-level measure wafer sequence		Version 2
Higher Order Intrafield Wafer Alignment		Disabled
Horizontal Stage Alignment Capture Strategy		Perform HSA capture
IF Cap Cooling Water Cabinet		IFCWC absent
IH Controlled Parameter Monitoring		Parameter Monitoring is not supported
IH NWE tank pressure sensor		One sensor
ILIAS Functionality For Lithoguide		Present
ILIAS PARIS top-plate bias voltage control mode.		Constant voltage level, using X2 port with optional dongle.
ILIAS Pupil measurement performance node		ILIAS Pupil measurement performance node 19
ILIAS SOMO reticle matching		Disabled
ILIAS Sensor Location		Both
ILIAS X2 Connector Dongle		None

ILIAS Zernike measurement performance node		ILIAS Zernike measurement performance node 19B
ILIAS lens setup		Absent
ILIAS number of supported Zernikes		ILIAS number of supported Zernikes 64
ILIAS sensor type chuck 1		Hyper NA MK5.5
ILIAS sensor type chuck 2		Hyper NA MK5.5
IPMI Reset type for IMCR rack		Reset using master host
IPMI Reset type for MMCR rack		Reset using master host
IRL barcode reader type		1D barcode reader is present at IRL
ISBO measure strategy during Stage Align		Once per Wafer
ISIS Functionality For Lithoguide		Absent
Identification of Positioning Module Supply Box version		Version 2
Identifier planar stage chuck 1 linear axis subversion		Version 1
Identifier planar stage chuck 2 linear axis subversion		Version 1
Illumination Specific Lens Enhancements		Disabled
Illumination modes		All illumination modes
Illuminator Machine Safety Hardware		IDPB
Illuminator Type		NA
Illuminator platform		Aerial XP
Illuminator type		190
Image optimizer generic focus corrections		Disable FOCUS optimizer generic focus corrections
Image quality data path arch		NA
Imaging Control Rack Configuration		IMCR4
Imaging Electronics Architecture		B Architecture
Imaging Fading Control		Lens set-up only
Imaging Generic Power Amplifier		Ten Axis Power Amplifier
Immersion		Present
Immersion CEX version		Version 1 or 2
Immersion Hood Sub version		Sub-Version 1
Immersion Hood SubSub version		Sub-Sub-Version D
Immersion Hood version		Version 5
Immersion hood heater configuration		Four segmented heaters on top
Improved Contrast Control		Absent
Improved Edge Field Leveling		Enabled
Improved FSM algorithm. Part of FIP-1 commercial package.		Enabled
Improved Fallback Leveling activation switch		Deactivates IFL on IFL-enabled machines
Improved Maintenance action scheduling.		Disabled

Improved conditioning in the ILIAS Lens Set Up test		Enabled, perform conditioning at the beginning of the test
Improved wafer reject mode		NA
Improvements for reticle handling		Enabled
In situ Wafer Table Stone Cleaning Hardware Version		NXT: Slow retract unit, microcontroller
In situ Wafer TableStone Cleaning		Present
In situ Wafer TableStone Cleaning Hardware Version		NA
Indication what kind of AM controller hardware is present		DICR
Inlet restriction for clean air		NA
Inline wafer heating correction type		No inline wafer heating control
Insert a delay time before starting a Lot (lens heating).		Disabled
Integrated Reticle Inspection System		NA
Integrated Reticle Inspection System Configuration.		Enable creation of OSIRIS viewable files for PPD2 systems.
Integrated Reticle Inspection System functionality		No particle detection functionality
Integrated Reticle Inspection System hardware.		IRIS hardware version not configured
Integrated Reticle Library		IRL_XP XCDA PURGED functionality
Intensity Calibration Per DOE		Disabled
Interferometer Electronics		SPMR
Interfield Scan Up Scan Down focus correction		Disabled
Intra-wafer-drift scale factor for TYPE4 reticle control		Use standard Reticle Control scale factor
Intrafield Higher Order Process Correction Mode		15 parameters (no scanning lens parameters) are supported
Intrafield Higher Order Process Corrections		Enabled
Intrafield Higher Order Process Corrections Per Exposure		Intrafield HOPC per exposure is Disabled
Intrafield Higher Order Process Corrections per subfield		Disabled
Intrafield Wafer Alignment		IFWA disabled
Intrafield fingerprint correction.		Functionality is not present.
Iris feature Scan		Present
Is NA accuracy measurement allowed?		Enabled
Is the UPS Ethernet connected to the Twinscan.		UPS is Ethernet connected to the Twinscan.
Is there a Restriction build in the POUH UPW Drain.		No restriction is built in the POUH UPW Drain.
Is this a machine with a safety PLC.		Safety PLC is available in the Twinscan.
Just-in-Time behavior of the wafer handler load robot		Just-in-Time behavior is disabled
LCI WaitWatcher plug-in		Absent

LCW Circuit set-up		Pressure Version 1
LCW leak detection functionality		LCW leak detection functionality for LCW cabinet is disabled
LCWC type for NXT platforms		LCWC-MK4L compatible
LEC Rack in Electronic Architecture		Absent
LS Drift correction strategy		XVSA and IVSA
LS Ry source		XVSA
LS focus node		LS focus node 6
LS spot coverage		Present
LS_PEMM_CONFIG		Absent
LTME Restriction in XCDA DU1		Version 1
LVT modeling version.		LVT model version 1 is enabled.
Laser Gas Life eXtension		Enable Laser Gas Life eXtension;
Laser capability for retrieving High Bandwidth Data		Laser does not provide Bandwidth Data
Layout Independent Leveling		Layout independent wafer leveling is not supported
Layout Version Number TIS Fiducial		TIS Fiducial Layout Version 1
Layout Version Number TIS Plate 1 on Chuck 1		TIS Plate 1 Layout Version 5.7
Layout Version Number TIS Plate 1 on Chuck 2		TIS Plate 1 Layout Version 5.7
Layout Version Number TIS Plate 2 on Chuck 1		TIS Plate 2 Layout Version 5.7
Layout Version Number TIS Plate 2 on Chuck 2		TIS Plate 2 Layout Version 5.7
Layout dependent overlay calibrations		Layout dependent overlay calibrations are disabled
Leave sensor plates with measure marks at a certain speed		Setting 2 : Leave sensor plates at limited speed
Lens Accelerometer Box version		Mark 1
Lens Active Vibration Absorber		Absent
Lens Circuit Water Flow		NA
Lens Control Strategy during lot production		Type 1 Lens state reset for Lot Correction
Lens Heating Feedback		Absent
Lens Heating Package		NA
Lens Model Reticle Stage Mode		Type A
Lens Top Micro Environment Sensors		No Pressure and Temperature sensors
Lens Top Tool Connection		Lens Top Tool can not be mounted on top of the Lens
Lens Type		98
Lens model optimization method		Lens set point calc. based on predefined constraints
Lens move during ESCAL		NA
Lens overpressure compensation during exposure.		Filtered lens overpressure
Level Sensor CPU configuration		Use board lf1

Level Sensor DAM version		DAM with initial PDA
Level Sensor Light Source type		Halogen or Energetiq EQ-99
Level Sensor Processing Rack		MMCR
Level Sensor peripheral configuration		TYPE1 - LM Mk3 or older and DAM NXE or older
Level sensor type		9-spots level sensor
Leveling Field Extensions Algorithm		Use the exposure field averaged values for field extension
Leveling Setpoint Smoothing		Do not use LS spot fading on edge dies
Leveling Verification Test for Lithoguide		Present
Leveling on single LS Spots		Do not use single spot leveling
Leveling with LS Spot Weight Update Algorithm		Selection of LS Spot Weight Update algorithm is not allowed
Levelling throughput improvement on measure side		NA
Light source selection, for FIR laser		NML type Light Source
Light source selection, for NIR laser		NML type Light Source
Light source selection, for green laser		Light source selection 2
Light source selection, for red laser		NML type Light Source
Light-source Architecture		Laser
Light-source Type		Cymer Laser: XLR 660 6.0kHz
Light-source Wave-length		193nm
Lightsource Mark		Mark1
Line of Sight Correction		Line of Sight Correction disabled.
Line of Sight Correction lens accelerometer sensors		Line of Sight Correction sensors absent.
Liquid Particle Counter Unit		NA
Litho InSight Alignment functionality		NA
Lithoguide Imaging Recipes		Absent
Load Robot Internal Docking		NA
Load Robot Wrist Assy Type		NA
Loadport barcode reader type		Original barcode reader at the loadports
Location of PARIS sensor on chuck 1		No PARIS sensor on chuck 1
Location of PARIS sensor on chuck 2		No PARIS sensor on chuck 2
Log missed translations		Disabled
Log total residuals in ADELexposureTrajectoriesReport		Log total residuals
Lot Alignment Report Encryption		NA
Lot Correction Sequence		Type E
Lot Overhead Reduction		LOR2
Lot Report Data Category		Enhanced Diagnostics
MALE used in production.		MALE is enabled in production.

MCH1 hardware version		No MCH1 hardware is present
MDL Viewer		Site View
Machine Architecture		NXT Machine Architecture
Machine Location		Customer Site
Machine Specification		pep-A Specification
Machine Status Lamp		4 Color
Machine Type		1950
Machine focus specification		Focus 1 Specification
Machine imaging specification		Imaging 1 Specification
Machine overlay matching method		BaseLiner MMO style using detrended HF-maps
Machine overlay specification		Overlay 1 Specification
Managed Switch 1 (MSW1) network configuration version		No managed switch 1 is configured in the AERC
Managed Switch 1 type		No MSW1 hardware present
Managed Switch 2 (MSW2) network configuration version		No Managed Switch 2 is configured
Managed Switch 2 type		No MSW2 hardware present
Managed Switch 3 type		No MSW3 hardware present
Managed Switch 4 type		No MSW4 hardware present
Managed Switch 5 type		No MSW5 hardware present
Managed Switch 6 type		No MSW6 hardware present
Matching different reticle groups		Disabled
Max alignment speed		NA
Maximum Reticle ID Length		24 Characters
Maximum numerical aperature (NA) allowed in Lot Production		level 0
Maximum wafer size allowed on the system		Maximum wafer size 300 mm
Measure and model strategy for vertical stage align		NA
Method for alignment of the laser beam		Align beam by optimizing pupil telecentricity params: LUBB
Method to optimize aligned positions		2 color recipes
Metroframe Circuit Water Cabinet		NA
Metroframe Temperature Performance level		NA
Metroframe type		NA
Metrology Focus grid HF correction		Disable the Focus grid HF correction
Metrology focus setup method		Focus setup calibration via CDM3 method
Metrology overlay setup method		BMMO metrology setup
Model switch for MACHINE_OVERLAY_STAB_CTRL = LEVEL_2A		Use old model of LEVEL_2
Modelling for MAXYS		NA
Motor Circuit Water Flow		NA

Move profile parameter configuration chuck 1		Move profile settings 3
Move profile parameter configuration chuck 2		Move profile settings 3
Move to first exposure strategy		First x-move and then y-move or diagonal move
Multi Focal Imaging Mode		Not applicable
Multi Functional Exchangeable Lens Element		Projection lens has no MF-EPLE
Multifunction Active Lens Element		2
Multifunctional Active Elements		2
Multilingual UI		Absent
NA Control Architecture		NA3 Half Bridge
NA Control Type		190
NA scaling improvements		NA scaling improvements enabled
NA1 motor type		None
NXE Arch. revision		no revision
NXE Reticle Backside Inspection System		Absent
NXT Arch. revision		revision 1_1
NXT test configuration		No test configuration
NexZ performance mode		Scanning NexZs
Nitrogen purging of Reticle Stage		RS is not purged
Number of Active Elements		
Number of Active Lens Elements		
Number of Active Manipulator Elements		
Number of Bi-directional Active Lens Elements		
Number of EXLE elements		1
Number of Half Dome Mirrors		2
Number of Lens NEXZ Manipulators		6
Number of Lens Z Manipulators Using Camdisk		
Number of RMCS clients		No clients
Number of Rxm		6
Number of Rym		6
Number of Semi-Active X-Y Lens Manipulators		6
Number of Z Lens Manipulators		6
Number of alignment marks at max throughput spec		28 marks
Number of bending points (mirrors).		2 mirrors.
Number of manipulable ELLE axes		6
Number of manual overrides for ESO2 and ESO3.		Level 1
Number of pre-amps available per Z-		

manipulator		
Number ofsupported fast Zernikes		ILIAS number of supported Zernikes 64
OADB Improved Dynamic Range		Enabled
OIU display hardware		OIU display is implemented by a Sun Ray thin client
ORION sensor version		No ORION version; sensor is not ORION
Obsolete, do not change!		NA
Online Lamp Peak		NA
Operating system of the CT Host		VxWorks
Optimized lens adjustment between WBW and TIS Reticle Align		NA
Option to apply the usage of HO marks in StageAlign		NA
Overlay Data Collection		Overlay Data Collection enabled.
Overlay Node		Level 0
PARIS HSA measurement strategy		Periodic
PARIS PSM scenario configuration		NA
PARIS Virtual RA Model Version Switch.		NA
PARIS configuration for DCO improvements		NA
PARIS plate shape measurement layout		NA
PARIS rejected pixels report		Disabled
PARIS reticle alignment		PARIS reticle alignment not supported
PARIS sensor performance nodes		PARIS performance node 19A
PCE Location		pce in APEX
PDGC functionality for UVLS		NA
PDOC quality indicator check		PDOC quality indicator functionality is present
PED control mode		Absent
PEP Alignment		No option available
PEP High SLIP		PEP High SLIP is disabled
PEP-ADC Intensity		NA
PGSG REV_ONE setpoint generator improvement		NA
PIPA boardtype		MK2
POB fine setup type		NA
PSE Location		pse in PSER
PSE exchanger functionality		PSE exchanger functionality not available
PSE type		XY polarization
PUPICOM		Absent
PUPICOM Architecture		Multi Spoke
PUPIL Measurement For Lithoguide		Present
PUPILIAS matching in terms of sigma measurement		Match ILIAS MK5 to MK4
PVP constraint to turn on/off reticle cooling		Reticle cooling functionality is not present

functionality		
PVP for disabling the laser burst interaction functionality		Enabled
Parameter indicates how long overlay data will be stored.		Short retention period.
Patch strategy		Patchlevel
Pattern Matcher		Present
Pattern Matcher Flexray		Freeform subrecipes referencing tuned pupil are not allowed
Pattern Matcher Full Chip		Absent
Pellicle-distortion overlay corrections		No pellicle-distortion corrections
Performance Enhancement Package		None
Physical location of OIU.		OIU is LEFT oriented.
Piezo Active Lens Mounts		Digital MK-2
Point-to-Point LS Machine Matching		Disabled
Polarization		Present
Polarization Shaping Element Retractor		PSER hardware installed in the machine
Polarized illumination amorph DOE.		Only unpolarized illumination.
Position of Spot Sensor on Chuck 1		Spot Sensor Position on Chuck 1 layout 4
Position of Spot Sensor on Chuck 2		Spot Sensor Position on Chuck 2 layout 4
Positioning Module configuration of chuck 1		Normal configuration
Positioning Module configuration of chuck 2		Normal configuration
Possible triggers for disk cleaning		M-action can trigger disk cleaning
Power rack configuration		Phase_1/XTIII electronics (reduced safety settings)
Pre-aligner retry mechanism during continuous rotate		Retry mechanism enabled
Process Dependent Gain Correction		Present
Process Window Optimizer		Version 1
Projection GPA Configuration Version		Version 2
Provides information about number of RS encoders		3 RS encoders
Proximity Matching		Present
Pupil TIS angular sensitivity calibration and correction		TIS Pupil Measurement will not be improved
Pupil forming optics		FlexRay
Pupil measurements with ILIAS		Present
Pupil qualification method		Geometric centre method
QXE Architecture Revision		No revision
QXT Architecture Revision		No revision
RA capture before CEX. Protected.		RA capture in expose sequence always after CEX
RCW1 circuit leak detection		No leak detection
RCW1 leak detection functionality		Leak detection functionality for RCW1 cabinet is disabled.

RCW2 circuit leak detection		No leak detection
RCWC firmware download		Enabled
RCWC mk3 Firmware update		Firmware update enabled
RCWC type		RCWC-Mk2 compatible
REMA architecture		XTREMA
RH Logistics Version Override		RH Logistics is not overridden
RHC fallback method		No fallback
RS Object Field		Shifted 19x0
RS_TORSION_CONTROL PVP		Torsion control disabled
Radial Basis Function Alignment Model		Disabled
Rapid prototyping using Python to control the machine.		Disable rapid prototyping.
ReMa mark		Mark3
Recipe Creator		Absent
Reduce AGILE2 measurement time for UVLS		NA
Reduce Wafer Stage fly-by move disturbance		NA
Reduce focus error for NA changes		NA
Reduce high overlay sensitivities for RS-Rz		NA
Reduce wafer-load-offset tolerance of centring unit to 25 um		Standard
Reduced capture range for TIS scans		NA
Reference Axis Performance Level		Level 1
Relative direction of ws to rs on the X axis		Same
Reorder Lot Service		Present
Report if a Recipe was modified by remote Host or Operator.		Do not report how Recipe was changed.
Reporting of K9/K10 coefficients from reticle alignment		RA_K9_K10_DATA_COLLECTION is Disabled
Reporting of the residuals expected to be seen in resist		Lens finger print, lens model residuals and image tuner
Reporting standard for no-value wafer align data		No-value is not reported
Reset type for VME racks		Serial reset
Reticle Align High Precision		Present
Reticle Balance Mass 1 amp.		550V25A: PAAC XT rev3
Reticle Balance Mass 2 amp.		550V25A: PAAC XT rev3
Reticle Carrier Location		Left
Reticle Carrier Tag Reader		Present
Reticle Exchange Type Version 2		Retex Option: G
Reticle Handler Machine Architecture		Reticle Handler is designed to handle reticles in air.
Reticle Handler type		RH Mark IV
Reticle Heating Control		Reticle Heating Control for NEXZ elements in scanning mode

Reticle Level Polarization Sensor		Present
Reticle Size		6 inch
Reticle Stage Chuck Cleaning Configuration		No valid cleaning configuration
Reticle Stage Chuck Type		TYPE_8: Two part symmetric chuck, wide clamps [Double Entry:] Magn. Grav. Comp. Changed Lens Top
Reticle Stage Lenscooler Box		Lenscooler Box with anti-aliasing Filter
Reticle Stage Long Stroke Config		TYPE_7:moving frame with iron less motor
Reticle Stage Long Stroke Motor Type		Cobalt Ferro 18 teeth
Reticle Stage Long Stroke Y11 amp.		550V25A: PAAC XT rev3
Reticle Stage Long Stroke Y12 amp.		550V25A: PAAC XT rev3
Reticle Stage Long Stroke Y13 amp.		550V25A: PAAC XT rev3
Reticle Stage Long Stroke Y21 amp.		550V25A: PAAC XT rev3
Reticle Stage Long Stroke Y22 amp.		550V25A: PAAC XT rev3
Reticle Stage Long Stroke Y23 amp.		550V25A: PAAC XT rev3
Reticle Stage Measurement System on Scan		Heidenhain Encoders
Reticle Stage Short Stroke X amp.		PADC 52V/6A
Reticle Stage Short Stroke Y11 amp.		PADC 130V/24A
Reticle Stage Short Stroke Y12 amp.		PADC 130V/24A
Reticle Stage Short Stroke Y21 amp.		PADC 130V/24A
Reticle Stage Short Stroke Y22 amp.		PADC 130V/24A
Reticle Stage Short Stroke Z1 amp.		PADC 52V/6A
Reticle Stage Short Stroke Z2 amp.		PADC 52V/6A
Reticle Stage Short Stroke Z3 amp.		PADC 52V/6A
Reticle Stage Short Stroke Z4 amp.		PADC 52V/6A
Reticle Streaming 3		NA
Reticle Streaming Options		Reticle Streaming 1
Reticle Temperature Sensor		RTS hardware is present
Reticle align capture		NA
Reticle exchange type		Retex option: G
Reticle load protection for too wide/wrongly placed pellicle		Disabled
Reticle shape correction		Enabled
Reticle streaming		NA
Reticle streaming II		NA
Reticle streaming lite		NA
Reuse the ASC corrections based on recipe id and group id		Disables grouping of ASC correction sets
Rotating Stone Wafer Table Cleaning		Disable rotating stone wafer table cleaning
Rough Cooling Water Cabinet 1 (RCWC1) cooling water flow		Full performance flow
Router hardware type		No router hardware present
SAMOS Stray Light Test For Lithoguide		Present

SDM test on machines without SAXY elements		Disabled
SECS Wafer Level Corrections		Not allowed
SMASH 2 color to 4 color support		SMASH 2 color to 4 color upgrade is disabled
SMASH Reuse Capture Information in Stage Alignment		Capture is done and reused per lot.
SPM Dual Speed Data Delay		Present
SPM WS Encoder drift scan		Version 1
SPM Wafer Stage Encoder Measurement System Type		2D Encoders
SPM zeroing plane where zero sensors are configured.		NA
SPM_EZCAP_FW_VERSION		SPM_EZCAP_FW_VERSION_2
Save throughput data to the disk		Enabled
Scaling of Lot Correction field effects		Scaling of Lot Correction functionality is absent
Scanning Energy Sensor Calibration		Scanning Energy Sensor Calibration
Select BF3u2 mark positions for Mk5.x PARIS plate		Use non-compliant BF3u2 mark position
Select the version of FOCAL modeling CPD application.		Legacy modeling
Selects wafer correction mode		No wafer corrections
Set PUPICOM use		N_A
Set UNICOM use		N_A
Set setpoint acceleration jerk ratio to constant or variable		Variable
Settle time reduction to improve the throughput		Don't care
Setup sensor board version		Setup SSD version LSDB
Short Chuck-Thermal-Conditioning Post Condition		Setting 1 On BES with BES on
Shot Data Collection		Present
Skip LS spots on TIS gratings for iVSA		Disabled
Skip capture on Horizontal Stage Alignment		NA
Skip capture on horizontal stage alignment (HSA)		Do perform catpure during HSA on PARIS plate
Small Alignment Marks Support		No Small Marks
Smart Lens Positioning Function Mode		Smart Lens Positioning functionality is disabled.
Smash increased scan-speed		SMASH increased scan-speeds are disabled
Smash sensor version		SMASH versions up to but not including Mk 3.3
Smooth Field Uniformity		Absent
Software support for the Active Plate Manipulator		Disabled
Specifies chuck1 config		Planar stage Immersion mark 3
Specifies chuck1 version		Version 2

Specifies chuck2 config		Planar stage Immersion mark 3
Specifies chuck2 version		Version 2
Specifies if system is a machine or a test tool		Not applicable
Specifies the Wafer Stage test configuration for WH		No special test configuration
Specifies which mark types are supported		ASML marks and custom marks
Spot Sensor Chuck 1		VLOC
Spot Sensor Chuck 2		VLOC
Spot Sensor Reticle Stage		Present
Spotsensor chuck 1 surface coating		SiO2
Spotsensor chuck 2 surface coating		SiO2
Spotsensor on chuck 1 present		Spotsensor on chuck 1
Spotsensor on chuck 2 present		Spotsensor on chuck 2
Stage Alignment Filter		Absent
Stage Alignment Phases		Fine stage alignment
Stage align just before FIWA		Enabled
Stages Sample Rate		5.0 kHz
Stand-alone Workstation		
Station 1 puck identification		No puck mounted
Station 2 puck identification		No puck mounted
Store Unit bottom pedestal type		Fixed pedestal
Store Unit slot hardware type		Regular Store Unit slots
Strategy for avoidance routing to Pre-CEX park position		Use the shortest route to Pre-CEX park position
Striping correction ILIAS sensor		Enabled
Sub-version of Reticle Stage Long Stroke Configuration		Four Hose Reticle Cooling Configuration
Support chuck specific dose offsets via SECS		Disabled
Support chuck specific focus offsets via SECS		Disabled
Supported FIWA actuation modes		6 Par
Swap bridge 1 type		Swap bridge mark 3.2
Swap bridge 2 type		Swap bridge mark 3.2
Switch INFORMPRO2 Data Package reporting		InformPro2 is unavailable
Switch between default and reduced IH flyheight		NA
Switching stages sample frequency between 10 and 20kHz		10kHz stages servo control
System Startup/Shutdown screen type		Select Motif screen
System drift correction sensor		ILIAS is used for system drift correction
THFFC FDE model lens dependent		Enabled

TIS Advanced Coating Offset Calibration		Disabled
TIS Power switching		Enabled
TIS Reticle Alignment Vert Model Params		Z_Ry
TIS diffuser		TIS diffuser absent
TIS overlay and TPT node		TIS Overlay and Throughput Performance Node 19E
TIS plate deformation correction		Enabled
TIS plate usage in reticle align		NA
TIS plate usage in stage align		SA can skip the TIS1 measurements
TIS trigger mechanism		Use external trigger mechanism
TIS-like PARIS reticle alignment model		NA
TIS_ITOP		Disabled
TOP HD		Present
Test Table		Absent
Test Table Z Axis		Worm Wheel
Test table architecture		Aerial XP
The cpu for 2DM software.		Absent
The type of number cruncher board (NCB)		NA
The version of IADB board		Unspecified IADB version
The version of OADB (Optical Analog Digital converter Board)		OADB Version Mk2
To enable the closing wafer refresh functionality		Enabled
To identify the hw settings and config for Bridge BES flow		This indicates that the SBW_BES underpressure is at -35 kPa
Track Pre-warning signal (APR)		APR enabled
Trajectory Shaping (fading)		Is disabled
Turns on second waferstage host in atca rack		WS2 host is present, and CSGR must try to boot it
Turns on third waferstage host in AMCR rack		WS3 host is present, and CSGR must try to boot it
TwinScan operating altitude after SAT		Low operating altitude
Twinscan GUI display location		Twinscan is displayed at the OIU display
Twinscan autostart		Twinscan autostart is enabled
Type of 1st general purpose amp		TAPA
Type of 5th general purpose amp		TAPA
Type of Air Gauge		TYPE_1: Initial air gauge (-25.5mm)
Type of LS capture		Scanning
Type of MDRC used.		Type number of used MDRC: 2
Type of NEXZ actuator		NEXZ with 885nm range (NO3)
Type of PARIS sensor on chuck 1		No PARIS sensor on chuck 1
Type of PARIS sensor on chuck 2		No PARIS sensor on chuck 2
Type of UV Level Sensor		Visible Level Sensor
Type of filter used in the mirror optics of the		No filter

UV-LS		
Type of immersion hood for immersion		Actuator Fixed Height
Type of inline cleaning cabinet		NA
Type of preclamp restriction in CF unit/rear PCA of chuck 1		1.0 mm restriction
Type of preclamp restriction in CF unit/rear PCA of chuck 2		1.0 mm restriction
Type of projection multiplexer board		MUX type LAMB
Type of wafertable on chuck 1 for immersion machine		SiSiC version 5.4
Type of wafertable on chuck 2 for immersion machine		SiSiC version 5.2
UNICOM		Present
UNICOM Architecture		58 Motors
UPWC Mark 1 Process Cooling Water (PCW) valve setting		NA
UV Shutter version		NA
UV level sensor spot correction		NA
Ultra Pure Water Cabinet (UPWC) version		UPWC Mark 2
Unicom gray filter configuration		gray filter configuration has a slot for only one filter
Unicom gray filter mode		Single gray filter mode
Unicom move check		Unicom move check enabled
Uniformity Improvement Package		Present
Universal Prealignment		Disabled
Unload Robot Wrist Assy Type		NA
Usage of Energy Sensor data by TIS		Enabled
Usage of wavelength data by TIS		Enabled
Use Sigma Calibration		no Sigma Calibration
Use Sigma WIP Preserving Offsets		no Sigma WIP Preserving Offsets
Use global wafer shape instead of wedge in fallback fields		Disabled
Use of 12COLOR in alignment reporting		Reporting disabled
Use validity ranges around UIP data when Enabled.		Use exact matching for UIP data
Version of the Air Control Cabinet (ACC)		ACC MK 5
Version of the Dual HSSL PCI card on the ZK SCCB		Version 1
Visibility and editability of ESO3 table machine constants		Disable visibility and editability
WH Dock spring leaf cam typ		Hard
WH Load Robot gripperpad type		Normal gripperpad
WH Robot Power Amplifier		CPM 20
WH Unload Robot gripperpad type		Normal gripperpad
WH temperature conditioning type		Fast performance type used for XTIV and higher.

WS dynamic full data report		Disabled
WS encoder plate suspension		WS encoder plates are suspended on vibration dampers
Wafer Alignment Model Mapping		Disabled
Wafer Alignment modeling modes		Only one wafer alignment model per model step
Wafer Carrier Location		Left
Wafer Handler Ambient Release throughput optimization		Disabled
Wafer Handler Brake Box Type identification		No Brake Box installed
Wafer Handler Manifold Heater		Usage of the manifold heater is prohibited
Wafer Handler Pre-aligner Type		Pre-aligner with air-bearing table
Wafer Handler Productivity		Wafer Handler Productivity Level 0
Wafer Handler Store Unit Bottom Table Type identification		No Table installed
Wafer Handler improved robot takeover positioning		Disabled
Wafer Handler motion architecture configuration		PID/GIOS Based motion control
Wafer Handler wrt BF Shifted in Z		NA
Wafer Handling Docking Plate		WH Docking Plate Docking Body
Wafer Handling Drying Unit		WH Drying Unit Present
Wafer Handling Load Robot Type		Scara Arm, 50 mm Z stroke
Wafer Handling Pneumatics		Standard
Wafer Handling Store Unit Type		WH Store Unit 4 Slotted
Wafer Handling TSU		WH TSU Heater Present Inactive
Wafer Handling Test configuration		No test configuration (real)
Wafer Handling Track Input		WH Wafer Track Input Via SU
Wafer Handling Unload Robot Type		Scara Arm, 50 mm Z stroke
Wafer Id Reader		NA
Wafer Level Overlay Corrections		Wafer level correction is disabled
Wafer Load Grid settings		Baseline
Wafer Load settings		NA
Wafer Mark Sensor		Absent
Wafer Size		300mm
Wafer Stage Configuration		Wafer Stage type 1 configuration
Wafer Stage Dynamic Disturbance Reduction		Disabled
Wafer Stage Expose Move Strategy		Version 1
Wafer Stage Exposure Defectivity Routing		Disabled
Wafer Stage Measurement System		Heidenhain encoders
Wafer Stage Type		Dual Chuck
Wafer Stage WEX TPT		Default WEX TPT
Wafer Stage WEX method.		Default WEX method

Wafer Stage measure to expose/expose to measure feed forward		Disabled
Wafer Stage to Airmounts feed forward functionality		Disabled
Wafer Switch		NA
Wafer Table Heater Control		Disabled
Wafer Table Reconditioning		Absent
Wafer Table unflatness overlay drift correction		Disabled
Wafer Track		Present
Wafer Unload settings		Wafer Unload sequence 3
Wafer Z-Map modeling algorithm		Wafer Z-Map modeling algorithm: Discrete
Wafer alignment layout import modes		Layout import not allowed
Wafer approval strategy		Standard wafer approval
Wafer path from Carrier		Directly to pre-aligner
Wafer positioning SIOB configuration		SIOB-5 installed
Wafer stage power cabinet electronics		Config 4
Wafer stage technology		Wafer stage planar drive
Wafer type used in the machine		300 mm - SEMI Notch
Wafer unload type		Wafer unload under baseframe control
Wafer warpage measurement hardware type		No wafer warpage measurement hardware installed
Wafer z-map type.		Type 2: On-the-fly setpoints - no GLC
WaferTable BES sensitivity setting		Level 1 Default
Wafers per Carrier		25
Warped wafer shape support		Disabled
Wavelength Adjustable		Adjustable
Wavelength range of the light source		DUV wavelength family: 248nm or 193nm
Wet Chuck Ex. while stay hovering (Chuck1=Exp,Chuck2=Mea)		Hovering is enabled during CEX
Wet Chuck Ex. while stay hovering (Chuck1=Mea,Chuck2=Exp)		Hovering is enabled during CEX
Wet Vacuum unit version in EIM		Type B WVAC EIM unit installed
Whether or not to perform self-lock		Self-lock must not be performed
Wide Pellicle Detection		Present
Wide Pellicle Detection Type		OPTICAL
X-Matching Generation		Machine Generation level 0
XCHA Distribution Unit Version		MK1 or MK2
XML Lot Report Content Level		Extended
XML output for LITHOGUIDE		Disabled
XT Architecture Revision		None
XT REMA MPAC board type		MPAC type 2
XVSA Spot Selection and Modeling		NA

Correction		
Z-capture on low reflectivity wafers		Z-capture on low reflectivity wafers is disabled.
ZERO Fiducial		ILIAS MK4
Zmap scan profile type for Wafer Zmap		Wafer Z-map using constant velocity scan profiles
Zoom Axicon Architecture		ZZA
Zoom Axicon Type		190
board configuration		OADB
dHDM optimization mode in lens models.		No dHDM actuation
eiHOPC range extension		Extended iHOPC range extension is disabled
extended docking interface at Prealigner		ECC_0MM
for ASML created PDOC and PDGC subrecipes deletion		Prevent deletion of ASML created PDGC and PDOC subrecipes
iHOPC corrections per exposure per wafer		iHOPC per exposure per wafer is not allowed
iHOPC corrections per image per wafer		iHOPC per image per wafer is not allowed
iHOPC per image per chuck		Is not allowed
iHOPC range extension K7, K12 and K13		IHOPC Ranges extension K7, K12 and K13 is enabled
iVSA subsampling for PARIS plate degradation		Use all measured spots for modeling
mbds control		Present
routing for ASML test purposes		Disabled
switch for 3DOF / 6DOF HDM		NA
switch for 3DOF HDM / 6DOF HDM / sHDM / dHDM		HDM_TYPE_6DOF
wildcard matching to use reticle heating TOPRC records		Reticle heating control calibration record reuse is mode0
xCWC firmware download		Enabled